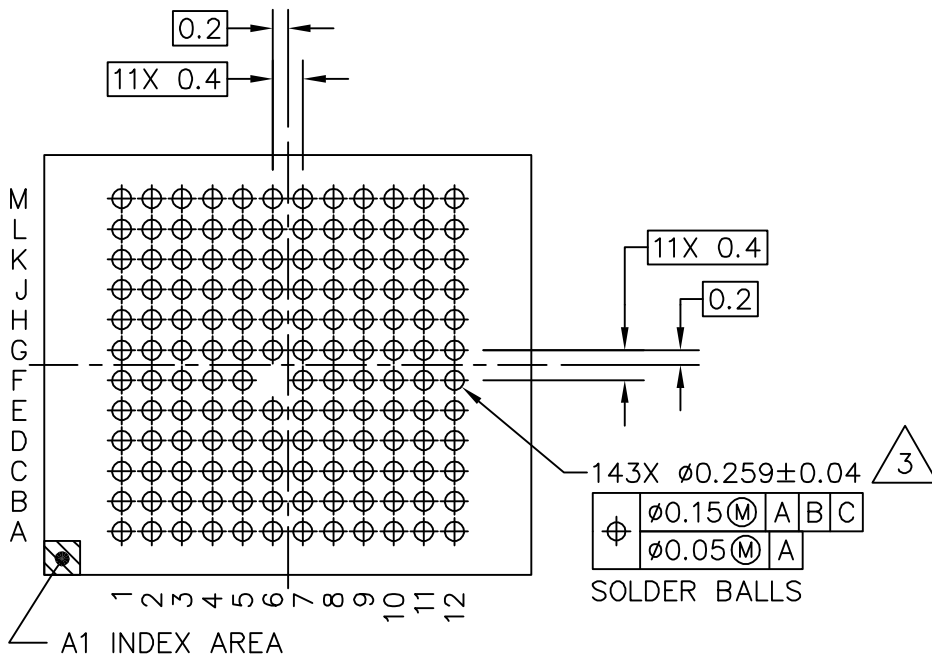
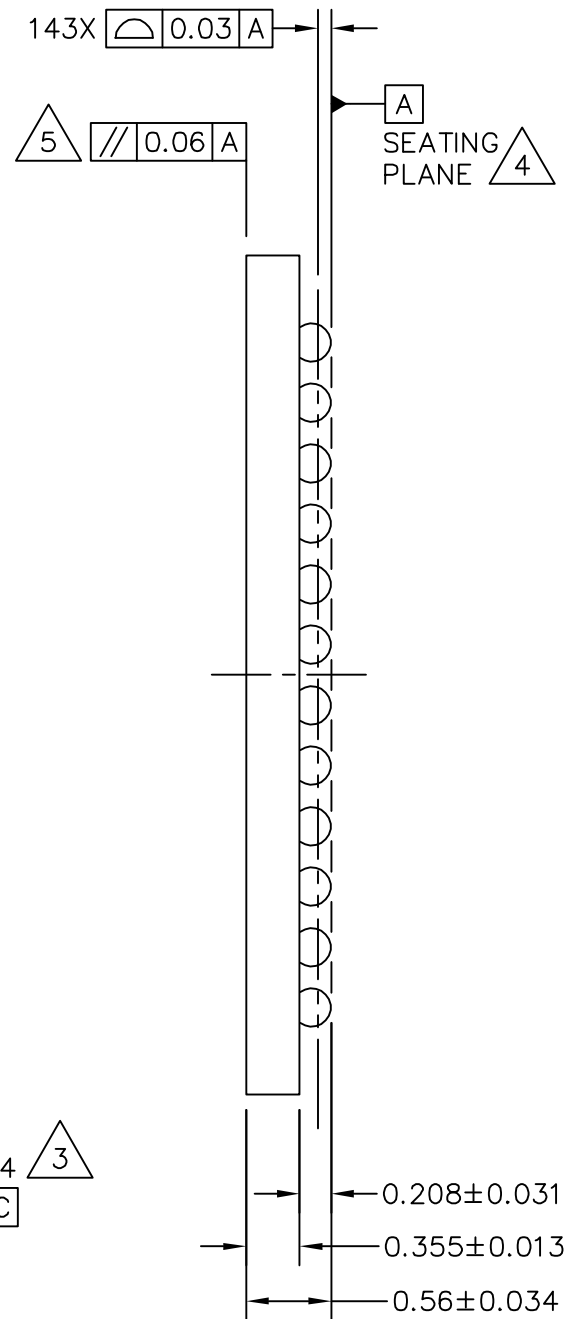


TOP VIEW



BOTTOM VIEW



VIEW D-D

RELEASED FOR EXTERNAL ASSEMBLY ONLY. THIS DESIGN ONLY MEETS EXTERNAL DESIGN AND ASSEMBLY RULES. MUST BE REVIEWED AND UPDATED BEFORE BEING ASSEMBLED INTERNALLY.

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TITLE: WAFER LEVEL CSP, 143 I/O, 6.44 X 5.55 X 0.56 PKG, 0.4MM PITCH	DOCUMENT NO: 98ASA00402D	REV: B
	STANDARD: NON-JEDEC	
	SOT1776-1	08 JAN 2016



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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